

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1    1. (currently amended): A magnetic head comprising:  
2            a substrate;  
3            a read head being fabricated upon said substrate;  
4            a P1 pole being fabricated upon said read head;  
5            a write gap layer being fabricated upon said P1 pole;  
6            a P2 pole tip being fabricated upon portions of said write gap layer, wherein said P2 pole  
7            tip includes a first sidewall portion being comprised of a seed layer and a second sidewall portion  
8            being comprised of electroplated material, and wherein said P2 pole tip has a thickness  
9            dimension t, and a base having a width dimension W;  
10            and wherein said seed layer is comprised of an integrally formed layer of material that  
11            forms said base of said P2 pole tip and a said first sidewall of said P2 pole tip that extends  
12            throughout said thickness t of said P2 pole tip.

1    2. (currently amended): A magnetic head as described in claim 1 wherein said electroplated  
2            material that comprises said second portion of said P2 pole tip plated upon said seed layer  
3            material that forms a said first sidewall of said P2 pole tip.

1    3. (original): A magnetic head as described in claim 1 wherein said seed layer material is  
2            formed with a thickness of approximately 50 Å to approximately 500 Å, and said electroplated  
3            material is formed with a thickness of approximately 100 Å to approximately 5000 Å.

1 4. (original): A magnetic head as described in claim 3 wherein said seed layer material  
2 thickness is approximately 250 Å and said electroplated material thickness is approximately  
3 1500 Å.

1 5. (original): A magnetic head as described in claim 3 wherein said seed layer material is  
2 comprised of NiFe and said electroplated material is comprised of NiFe.

1 6. (currently amended): A hard disk drive comprising:  
2 at least one hard disk being fabricated for rotary motion upon a disk drive;  
3 at least one magnetic head adapted to fly over said hard disk for writing data on said hard  
4 disk, said magnetic head including:  
5 a substrate;  
6 a read head being fabricated upon said substrate;  
7 a P1 pole being fabricated upon said read head;  
8 a write gap layer being fabricated upon said P1 pole;  
9 a P2 pole tip being fabricated upon portions of said write gap layer, wherein said P2 pole  
10 tip includes a first sidewall portion being comprised of a seed layer and a second sidewall portion  
11 being comprised of electroplated material, and wherein said P2 pole tip has a thickness  
12 dimension t, and a base having a width dimension W;  
13 and wherein said seed layer is comprised of an integrally formed layer of material that  
14 forms said base of said P2 pole tip and a said first sidewall of said P2 pole tip that extends  
15 throughout said thickness t of said P2 pole tip.

1 7. (currently amended): A hard disk drive as described in claim 6 wherein said electroplated  
2 material that comprises said second portion of said P2 pole tip plated upon said seed layer  
3 material that forms a said first sidewall of said P2 pole tip.

1 8. (original): A hard disk drive as described in claim 6 wherein said seed layer material is  
2 formed with a thickness of approximately 50 Å to approximately 500 Å, and said electroplated  
3 material is formed with a thickness of approximately 100 Å to approximately 5000 Å.

1 9. (original): A hard disk drive as described in claim 8 wherein said seed layer material  
2 thickness is approximately 250 Å and said electroplated material thickness is approximately  
3 1500 Å.

1 10. (original): A hard disk drive as described in claim 8 wherein said seed layer material is  
2 comprised of NiFe and said electroplated material is comprised of NiFe.

11-18 (withdrawn)

1 19. (currently amended): A magnetic head comprising:  
2 a substrate;  
3 a read head being fabricated upon said substrate;  
4 a P1 pole being fabricated upon said read head;  
5 a write gap layer being fabricated upon said P1 pole;

6           a P2 pole tip being fabricated upon portions of said write gap layer, wherein said P2 pole  
7   tip includes a base surface that is disposed upon said write gap layer and a first sidewall surface  
8   that is disposed generally perpendicularly to said base surface, and wherein said base surface and  
9   said first sidewall surface are comprised of an integrally formed layer of P2 pole tip seed layer  
10   material;

11           and wherein said P2 pole tip includes an electroplated material portion, and wherein said  
12   P2 pole tip includes a second sidewall surface that is disposed opposite to said first sidewall  
13   surface, and wherein said second sidewall surface is comprised of said electroplated material.

1   20. (currently amended): A magnetic head as described in claim 19 wherein said base  
2   surface defines a width W of said P2 pole tip and said first sidewall defines a thickness t of said  
3   P2 pole tip.

1   21. (currently amended): A magnetic head as described in claim 20, ~~wherein said P2 pole tip~~  
2   ~~further includes an electroplated material portion, and wherein said electroplated material portion~~  
3   is plated in part upon said first sidewall surface seed layer material.

1   22. (previously presented): A magnetic head as described in claim 21 wherein said seed  
2   layer material is formed with a thickness of approximately 50 Å to approximately 500 Å, and  
3   said electroplated material is formed with a thickness of approximately 100 Å to approximately  
4   5000 Å.

1 23. (previously presented): A magnetic head as described in claim 21 wherein said seed layer  
2 material thickness is approximately 250 Å and said electroplated material thickness is  
3 approximately 1500 Å.

1 24. (previously presented): A magnetic head as described in claim 21 wherein said seed layer  
2 material is comprised of NiFe and said electroplated material is comprised of NiFe.